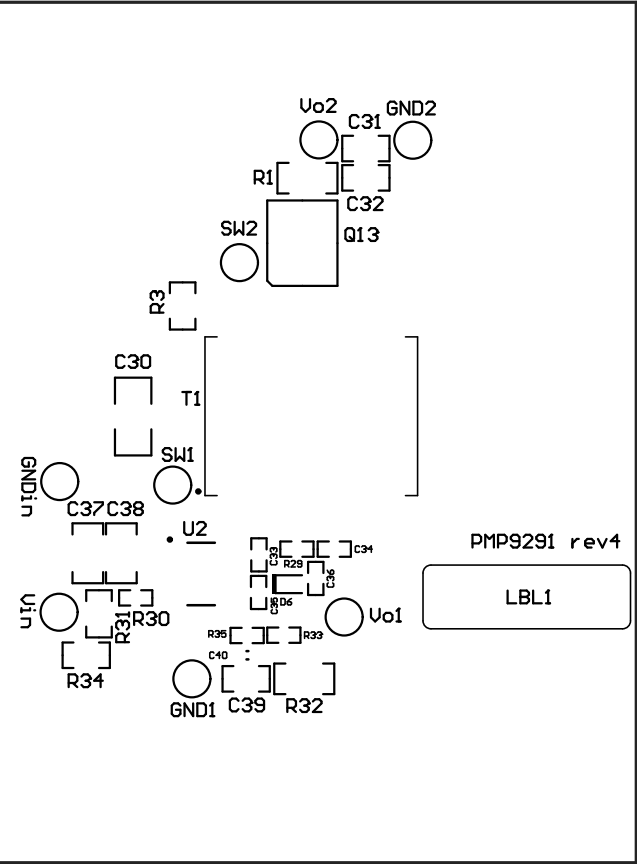
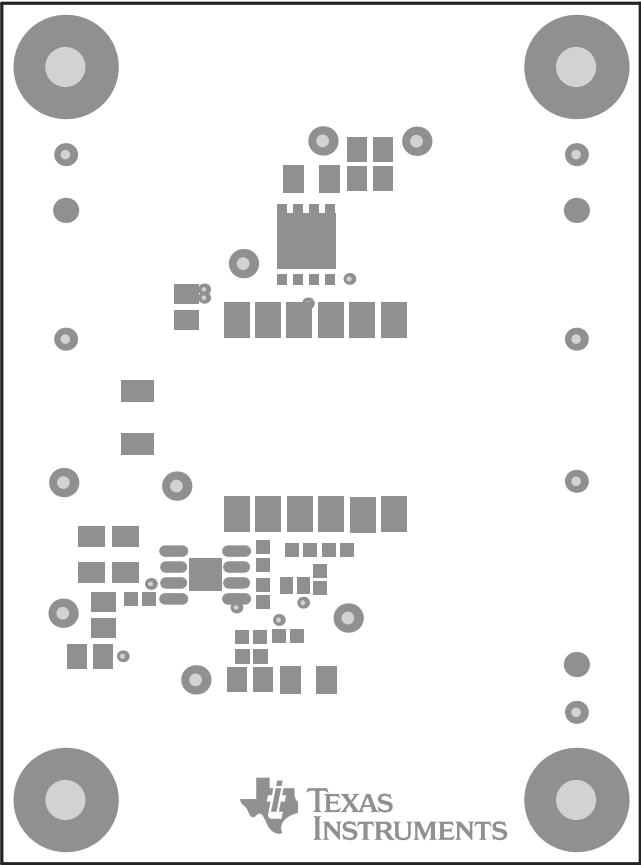
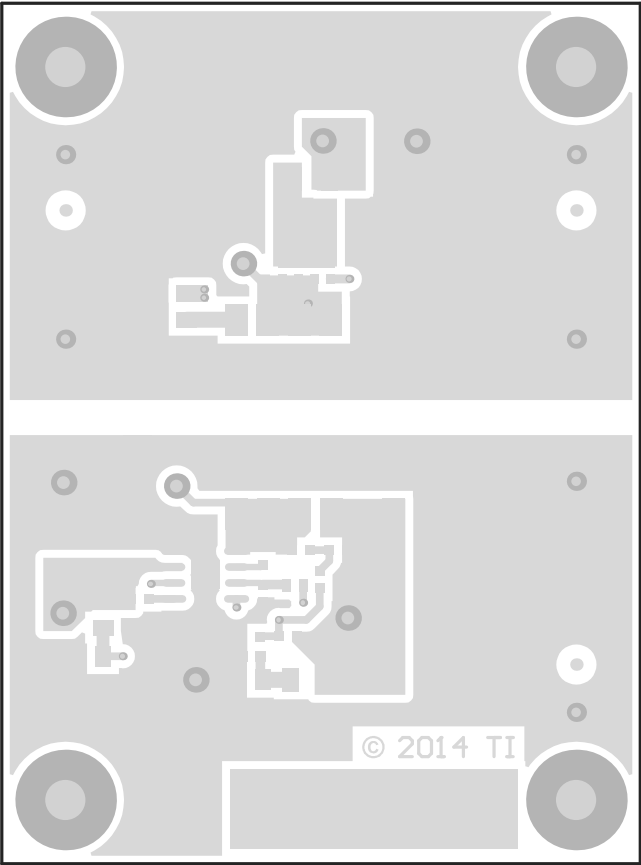




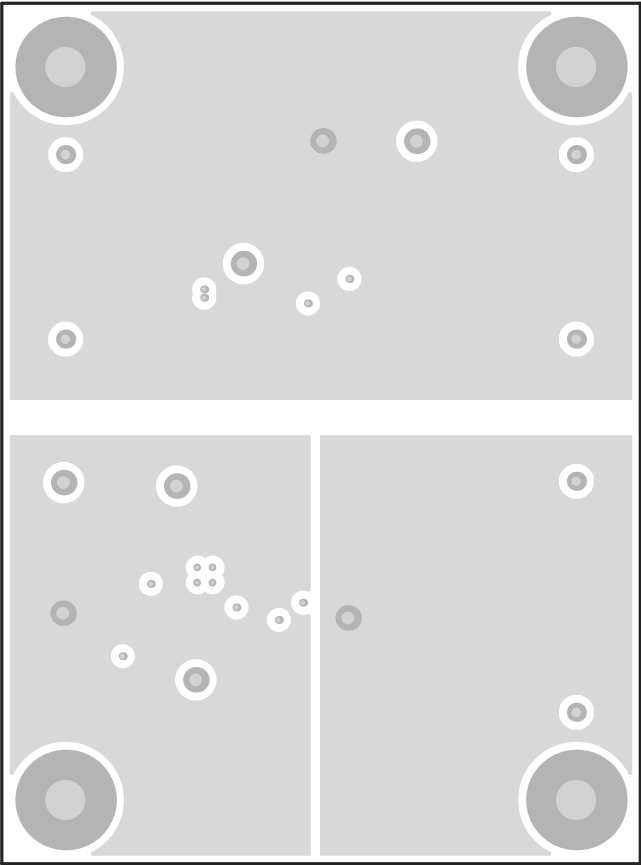
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9354	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 1/19/2015 2:58:44 PM	TEXAS INSTRUMENTS	



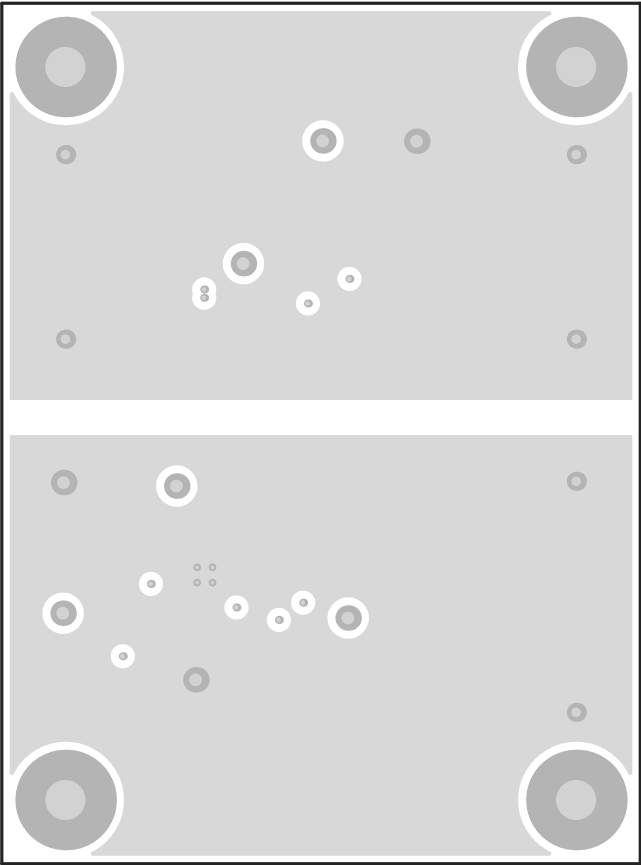
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9354	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 1/19/2015 2:58:45 PM	TEXAS INSTRUMENTS	



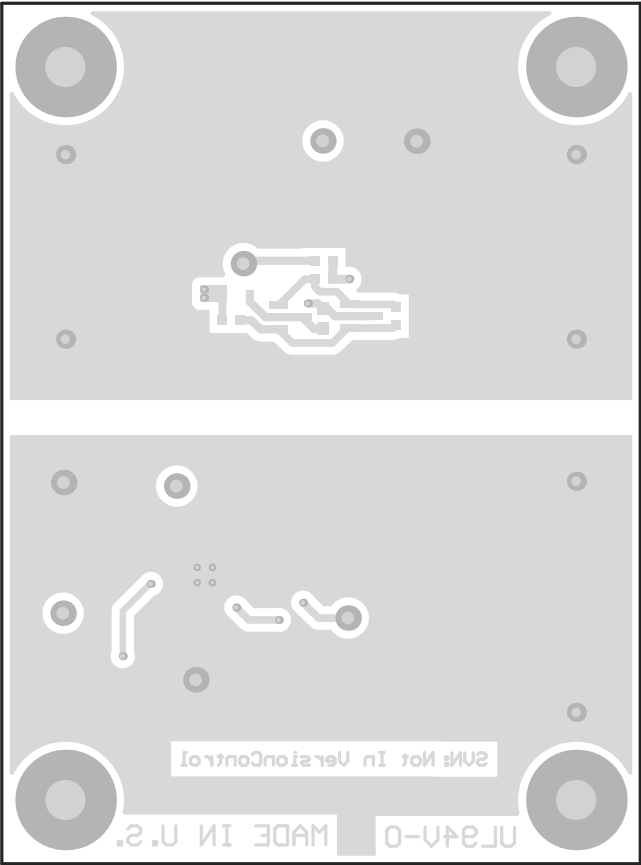
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9354	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 1/19/2015 2:58:46 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9354	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = MidLayer1	GENERATED : 1/19/2015 2:58:47 PM	TEXAS INSTRUMENTS	



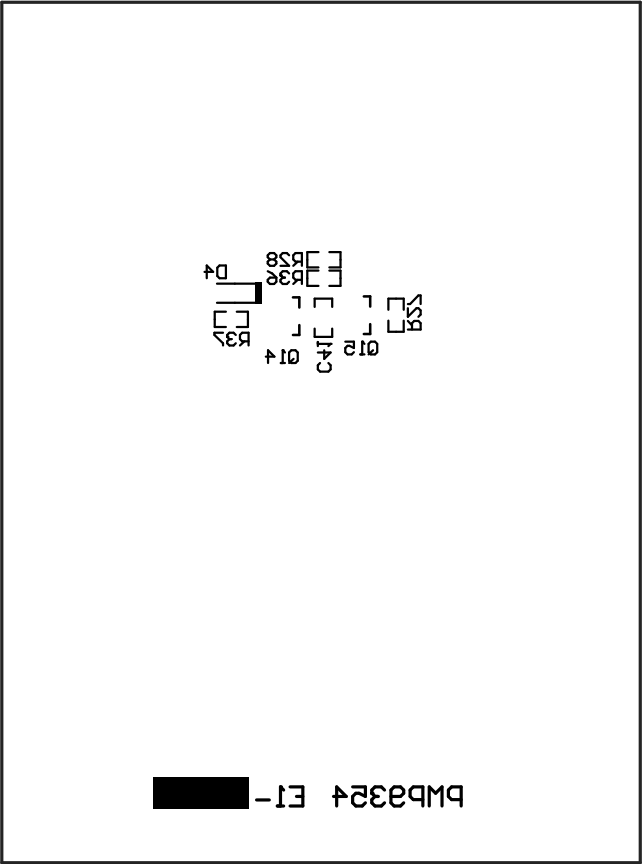
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9354	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = MidLayer2	GENERATED : 1/19/2015 2:58:47 PM	TEXAS INSTRUMENTS	



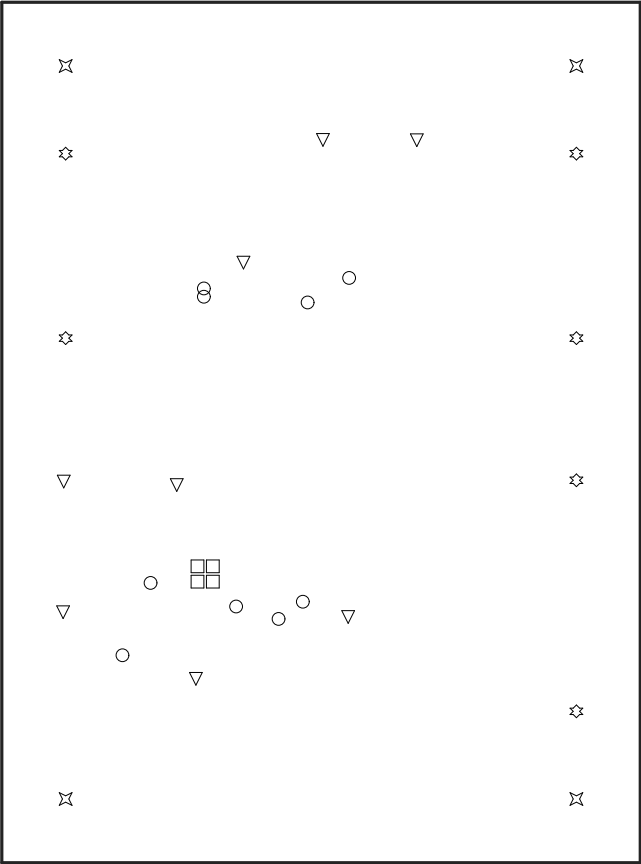
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9354	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 1/19/2015 2:58:48 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9354	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 1/19/2015 2:58:49 PM	TEXAS INSTRUMENTS	



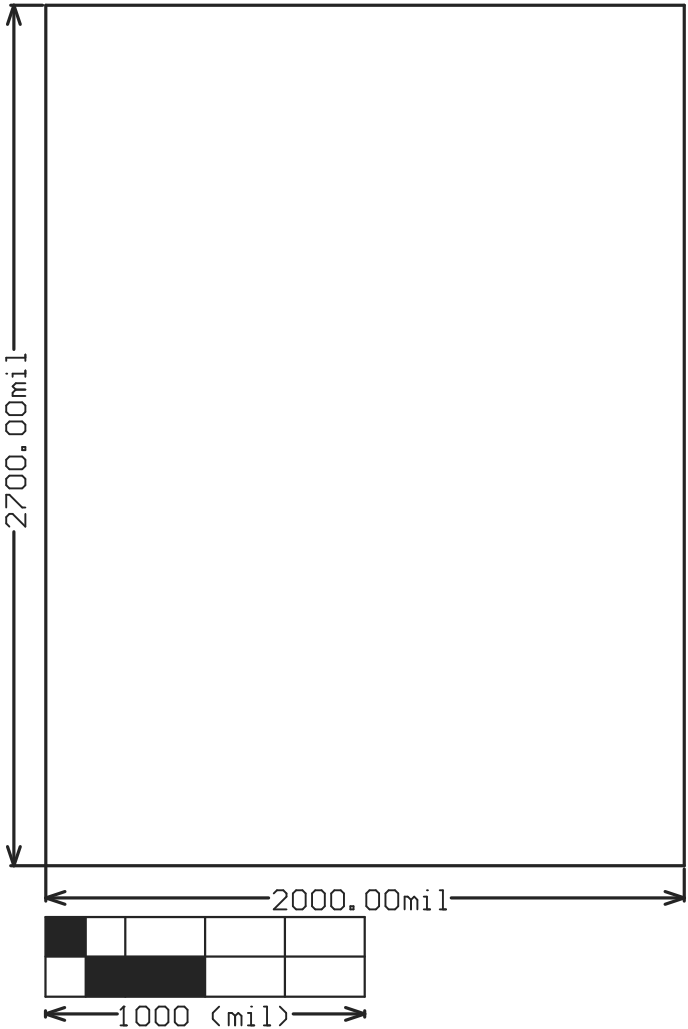
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9354	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 1/19/2015 2:58:50 PM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
□	4	12mil (0.305mm)	PTH	Round
○	9	15mil (0.381mm)	PTH	Round
☆	6	30mil (0.762mm)	PTH	Round
▽	8	40mil (1.016mm)	PTH	Round
✕	4	125.984mil (3.2mm)	PTH	Round
	31 Total			

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9354	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 1/19/2015 2:58:51 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9354	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 1/19/2015 2:58:52 PM	TEXAS INSTRUMENTS	

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